MARCH 1974 – REVISED MARCH 1988

- **Gated Serial Inputs**
- **Fully Buffered Clock and Serial Inputs**
- **Asynchronous Clear**

TYPE	TYPICAL MAXIMUM CLOCK FREQUENCY	TYPICAL POWER DISSIPATION
'164	36 MHz	21 mW per bit
'LS164	36 MHz	10 mW per bit

description

These 8-bit shift registers feature gated serial inputs and an asynchronous clear. The gated serial inputs (A and B) permit complete control over incoming data as a low at either input inhibits entry of the new data and resets the first flip-flop to the low level at the next clock pulse. A high-level input enables the other input which will then determine the state of the first flip-flop. Data at the serial inputs may be changed while the clock is high or low, but only information meeting the setup-time requirements will be entered. Clocking occurs on the low-to-high-level transition of the clock input. All inputs are diode-clamped to minimize transmission-line effects.

The SN54164 and SN54LS164 are characterized for operation over the full military temperature range of −55°C to 125°C. The SN74164 and SN74LS164 are characterized for operation from 0°C to 70°C.

SN54164, SN54LS164 . . . J OR W PACKAGE
SN74164 . . . N PACKAGE
SN74LS164 . . . D OR N PACKAGE
(TOP VIEW)

```
        ___ ___
A  [ 1  U 14 ] VCC
B  [ 2    13 ] QH
QA [ 3    12 ] QG
QB [ 4    11 ] QF
QC [ 5    10 ] QE
QD [ 6     9 ] CLR
GND[ 7     8 ] CLK
```

SN54LS164 . . . FK PACKAGE
(TOP VIEW)

```
         B  A  NC VCC QH
         3  2  1  20 19
QA [ 4               18 ] QG
NC [ 5               17 ] NC
QB [ 6               16 ] QF
NC [ 7               15 ] NC
QC [ 8               14 ] QE
         9  10 11 12 13
        QD GND NC CLK CLR
```
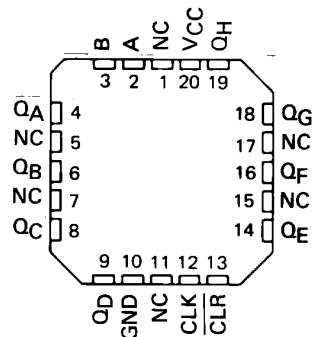
NC – No internal connection

FUNCTION TABLE

INPUTS				OUTPUTS		
CLEAR	CLOCK	A	B	Q_A	Q_B ...	Q_H
L	X	X	X	L	L	L
H	L	X	X	Q_{A0}	Q_{B0}	Q_{H0}
H	↑	H	H	H	Q_{An}	Q_{Gn}
H	↑	L	X	L	Q_{An}	Q_{Gn}
H	↑	X	L	L	Q_{An}	Q_{Gn}

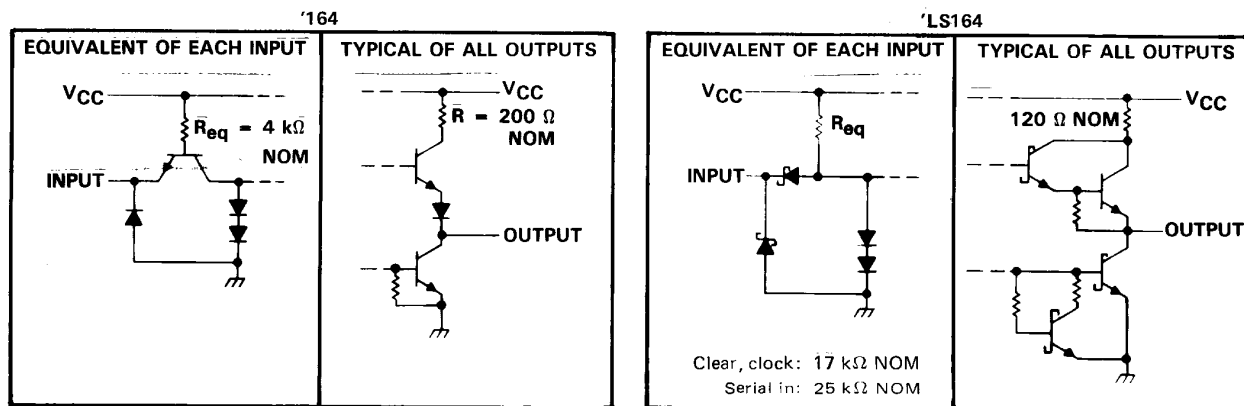H = high level (steady state), L = low level (steady state)
X = irrelevant (any input, including transitions)
↑ = transition from low to high level.
Q_{A0}, Q_{B0}, Q_{H0} = the level of Q_A, Q_B, or Q_H, respectively, before the indicated steady-state input conditions were established.
Q_{An}, Q_{Gn} = the level of Q_A or Q_G before the most-recent ↑ transition of the clock; indicates a one-bit shift.
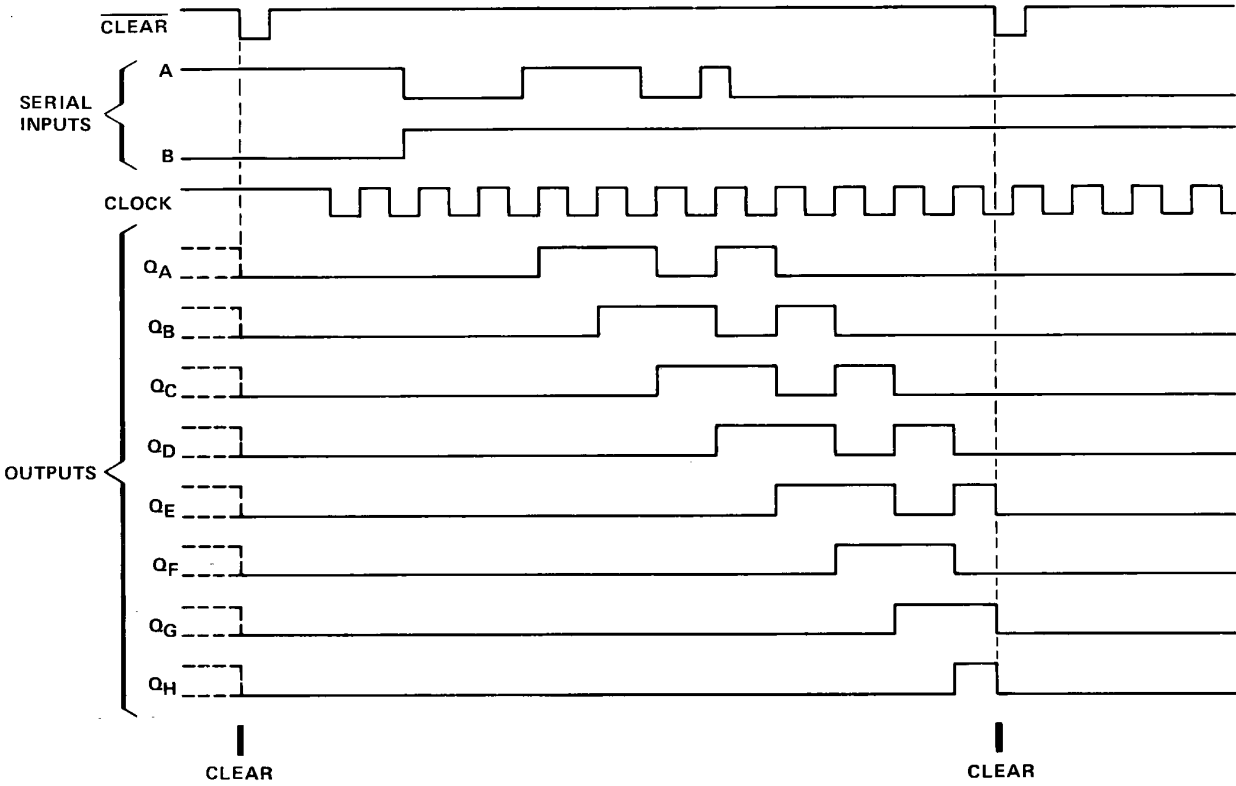
schematics of inputs and outputs

'164

EQUIVALENT OF EACH INPUT	TYPICAL OF ALL OUTPUTS
VCC — R_{eq} = 4 kΩ NOM — INPUT	VCC — R = 200 Ω NOM — OUTPUT

'LS164

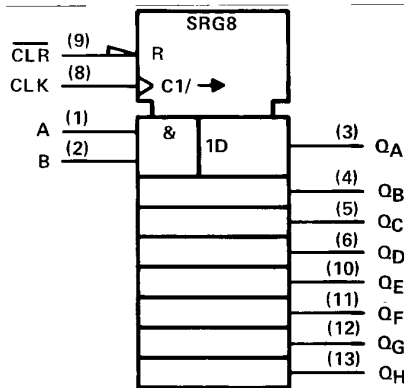| EQUIVALENT OF EACH INPUT	TYPICAL OF ALL OUTPUTS
VCC — R_{eq} — INPUT — Clear, clock: 17 kΩ NOM — Serial in: 25 kΩ NOM	VCC — 120 Ω NOM — OUTPUT

2

TTL Devices

typical clear, shift, and clear sequences

logic symbol†

†This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.
Pin numbers shown are for D, J, N, and W packages.

logic diagram (positive logic)

Pin numbers shown are for D, J, N, and W packages.

2

TTL Devices

TEXAS
INSTRUMENTS
POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

absolute maximum ratings over oprating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) .... 7 V
Input voltage .... 5.5 V
Operating free-air temperature range: SN54164 .... −55°C to 125°C
SN74164 .... 0°C to 70°C
Storage temperature range .... −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

	SN54164			SN74164			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}			−400			−400	μA
Low-level output current, I_{OL}			8			8	mA
Clock frequency, f_{clock}	0		25	0		25	MHz
Width of clock or clear input pulse, t_w	20			20			ns
Data setup time, t_{su} (see Figure 1)	15			15			ns
Data setup time, t_{su} (Clear Inactive) (see Figure 1)	20			20			ns
Data hold time, t_h (see Figure 1)	5			5			ns
Operating free-air temperature, T_A	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		SN54164			SN74164			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IH}	High-level input voltage			2			2			V
V_{IL}	Low-level input voltage					0.8			0.8	V
V_{IK}	Input clamp voltage	V_{CC} = MIN, I_I = −12 mA				−1.5			−1.5	V
V_{OH}	High-level output voltage	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.8 V, I_{OH} = −400 μA		2.4	3.2		2.4	3.2		V
V_{OL}	Low-level output voltage	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.8 V, I_{OL} = 8 mA			0.2	0.4		0.2	0.4	V
I_I	Input current at maximum input voltage	V_{CC} = MAX, V_I = 5.5 V,				1			1	mA
I_{IH}	High-level input current	V_{CC} = MAX, V_I = 2.4 V				40			40	μA
I_{IL}	Low-level input current	V_{CC} = MAX, V_I = 0.4 V				−1.6			−1.6	mA
I_{OS}	Short-circuit output current§	V_{CC} = MAX		−10		−27.5	−9		−27.5	mA
I_{CC}	Supply current	V_{CC} = MAX, See Note 2	$V_{I(clock)}$ = 0.4 V		30			30		mA
			$V_{I(clock)}$ = 2.4 V		37	54		37	54	

† For conditions shown at MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ Not more than two outputs should be shorted at a time.
NOTE 2: I_{CC} is measured with outputs open, serial inputs grounded, and a momentary ground, then 4.5 V, applied to clear.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
f_{max}	Maximum clock frequency		C_L = 15 pF	25	36		MHz
t_{PHL}	Propagation delay time, high-to-low-level Q outputs from clear input	R_L = 800 Ω, See Figure 1	C_L = 15 pF		24	36	ns
			C_L = 50 pF		28	42	
t_{PLH}	Propagation delay time, low-to-high-level Q outputs from clock input		C_L = 15 pF	8	17	27	ns
			C_L = 50 pF	10	20	30	
t_{PHL}	Propagation delay time, high-to-low-level Q outputs from the clock input		C_L = 15 pF	10	21	32	ns
			C_L = 50 pF	10	25	37	

TEXAS
INSTRUMENTS
POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . 7 V
Input voltage . . . . 7 V
Operating free-air temperature range: SN54LS164 . . . . −55 °C to 125 °C
SN74LS164 . . . . 0 °C to 70 °C
Storage temperature range . . . . −65 °C to 150 °C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN54LS164			SN74LS164			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.7			0.8	V
I_{OH}	High-level output current			−0.4			−0.4	mA
I_{OL}	Low-level output current			4			8	mA
f_{clock}	Clock frequency	0		25	0		25	MHz
t_w	Width of clock or clear input pulse	20			20			ns
t_{su}	Data setup time (See Figure 1)	15			15			ns
t_{su}	Clear inactive setup time (See Figure 1)	20			20			ns
t_h	Data hold time (See Figure 1)	5			5			ns
T_A	Operating free-air temperature	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS[†]		SN54LS164			SN74LS164			UNIT
			MIN	TYP[‡]	MAX	MIN	TYP[‡]	MAX	
V_{IK}	V_{CC} = MIN, I_I = −18 mA				−1.5			−1.5	V
V_{OH}	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = MAX, I_{OH} = −0.4 mA		2.5	3.5		2.7	3.5		V
V_{OL}	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = MAX	I_{OL} = 4 mA		0.25	0.4		0.25	0.4	V
		I_{OL} = 8 mA					0.35	0.5	
I_I	V_{CC} = MAX, V_I = 7 V				0.1			0.1	mA
I_{IH}	V_{CC} = MAX, V_I = 2.7 V				20			20	µA
I_{IL}	V_{CC} = MAX, V_I = 0.4 V				−0.4			−0.4	mA
I_{OS}	V_{CC} = MAX		−20		−100	−20		−100	mA
I_{CC}	V_{CC} = MAX, See Note 3			16	27		16	27	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
[‡]All typical values are at V_{CC} = 5 V, T_A = 25 °C.
[§]Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.
NOTE 3: I_{CC} is measured with outputs open, serial inputs grounded, the clock input at 2.4 V, and a momentary ground, then 4.5 V applied to clear.

switching characteristics, V_{CC} = 5 V, T_A = 25 °C

| PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{max}	Maximum clock frequency		25	36		MHz
t_{PHL}	Propagation delay time, high-to-low-level Q outputs from clear input	R_L = 2 kΩ, C_L = 15 pF, See Figure 1		24	36	ns
t_{PLH}	Propagation delay time, low-to-high-level Q outputs from clock input			17	27	ns
t_{PHL}	Propagation delay time, high-to-low-level Q outputs from clock input			21	32	ns

2

TTL Devices

PARAMETER MEASUREMENT INFORMATION

TEST CIRCUIT
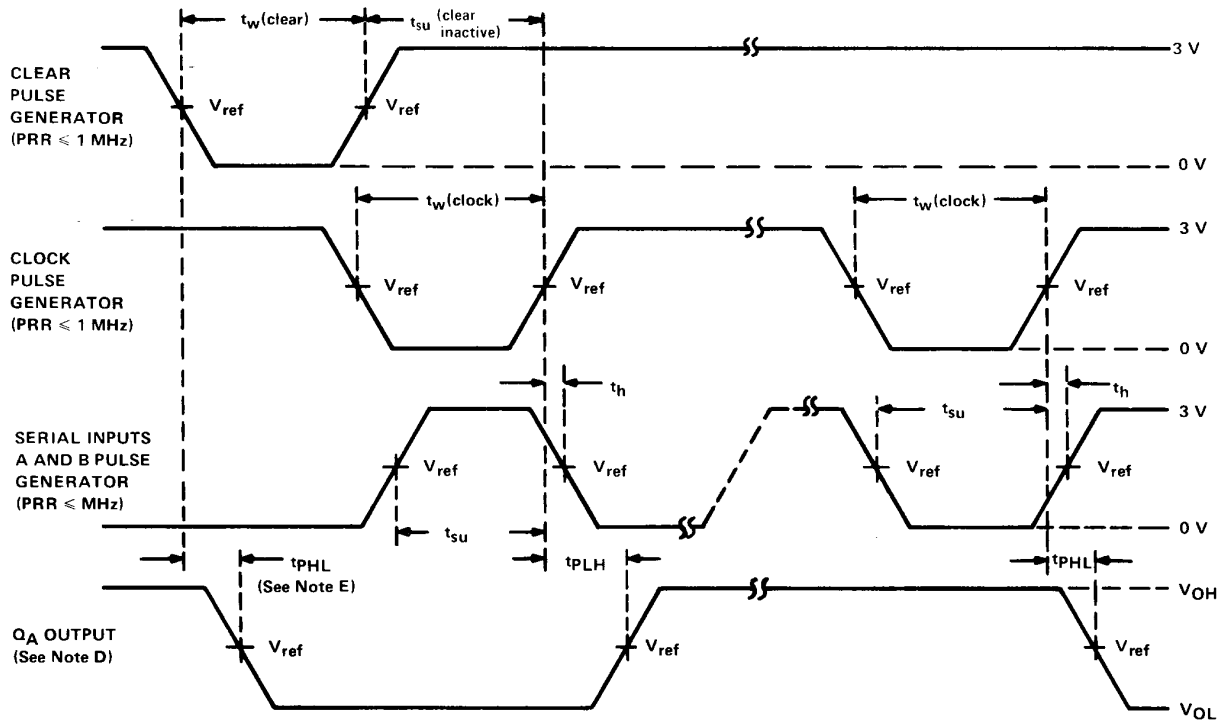
VOLTAGE WAVEFORMS

NOTES: A. The pulse generators have the following characteristics: duty cycle ≤ 50%, $Z_{out} \approx 50\ \Omega$; for '164, $t_r \leq 10$ ns, $t_f \leq 10$ ns; and for 'LS164, $t_r \leq 15$ ns, $t_f \leq 6$ ns.
   B. C_L includes probe and jig capacitance.
   C. All diodes are 1N3064 or equivalent.
   D. Q_A output is illustrated. Relationship of serial input A and B data to other Q outputs is illustrated in the typical shift sequence.
   E. Outputs are set to the high level prior to the measurement of t_{PHL} from the clear input.
   F. For '164, $V_{ref} = 1.5$ V; for 'LS164, $V_{ref} = 1.3$ V.

FIGURE 1—SWITCHING TIMES

TEXAS
INSTRUMENTS
POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
JM38510/00903BCA	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
JM38510/30605B2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30605B2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30605BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30605BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30605BDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30605BDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30605SCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30605SCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30605SDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30605SDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SN54164J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN54164J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN54LS164J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54LS164J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN74164N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74164N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS164D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS164J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS164N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS164N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS164N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS164N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS164NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS164NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS164NSR	ACTIVE	SO	NS	14	2000	Green (RoHS &	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
						no Sb/Br)		
SN74LS164NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54164J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SNJ54164J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SNJ54164W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
SNJ54164W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
SNJ54LS164FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS164FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS164J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS164J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS164W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS164W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DIM / PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	——	——	——	——
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

B

14   8

1   7

0.065 (1,65)
0.045 (1,14)

0.005 (0,13) MIN

0.060 (1,52)
0.015 (0,38)

0.200 (5,08) MAX

Seating Plane

0.130 (3,30) MIN

0.026 (0,66)
0.014 (0,36)

0.100 (2,54)

A

0°-15°

0.014 (0,36)
0.008 (0,20)

4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).
         B. This drawing is subject to change without notice.
         C. This package is hermetically sealed with a ceramic lid using glass frit.
         D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
         E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R–GDFP–F14)   CERAMIC DUAL FLATPACK

Base and Seating Plane

$\dfrac{0.260\ (6,60)}{0.235\ (5,97)}$

$\dfrac{0.045\ (1,14)}{0.026\ (0,66)}$

$\dfrac{0.080\ (2,03)}{0.045\ (1,14)}$

$\dfrac{0.006\ (0,15)}{0.004\ (0,10)}$

0.280 (7,11) MAX

$\dfrac{0.019\ (0,48)}{0.015\ (0,38)}$

1

14

0.050 (1,27)

$\dfrac{0.390\ (9,91)}{0.335\ (8,51)}$

0.005 (0,13) MIN
4 Places

7

8

$\dfrac{0.360\ (9,14)}{0.250\ (6,35)}$

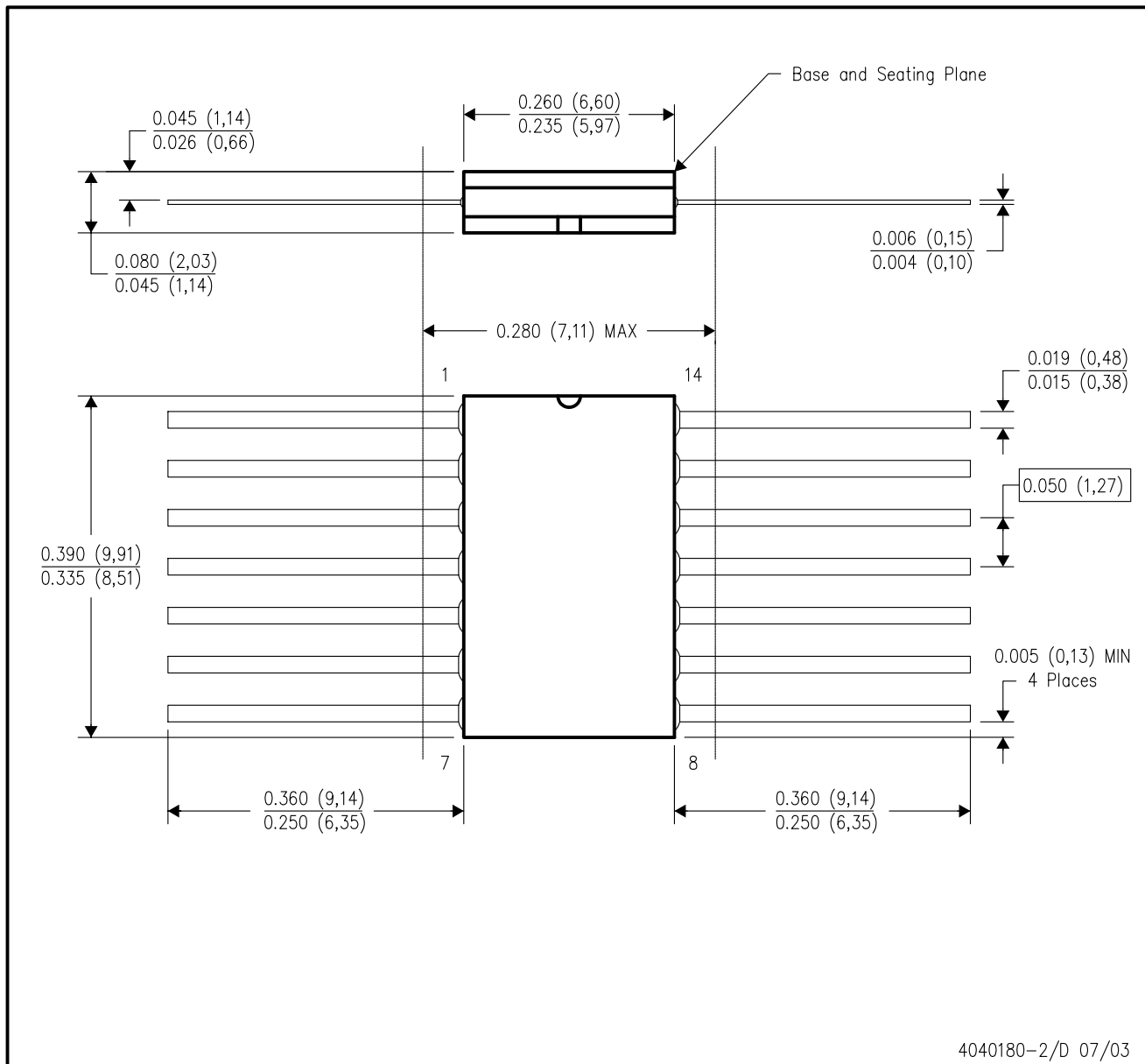$\dfrac{0.360\ (9,14)}{0.250\ (6,35)}$

4040180–2/D 07/03

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
         C.   This package can be hermetically sealed with a ceramic lid using glass frit.
         D.   Index point is provided on cap for terminal identification only.
         E.   Falls within MIL STD 1835 GDFP1–F14 and JEDEC MO–092AB

FK (S-CQCC-N)**   **LEADLESS CERAMIC CHIP CARRIER**

28 TERMINAL SHOWN

NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.739 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)

0.020 (0,51) / 0.010 (0,25)

0.020 (0,51) / 0.010 (0,25)

0.080 (2,03) / 0.064 (1,63)

0.055 (1,40) / 0.045 (1,14)

0.045 (1,14) / 0.035 (0,89)

0.028 (0,71) / 0.022 (0,54)

0.045 (1,14) / 0.035 (0,89)

0.050 (1,27)

4040140/D 10/96

NOTES: A. All linear dimensions are in inches (millimeters).
        B. This drawing is subject to change without notice.
        C. This package can be hermetically sealed with a metal lid.
        D. The terminals are gold plated.
        E. Falls within JEDEC MS-004

TEXAS INSTRUMENTS

POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

N (R−PDIP−T**)

16 PINS SHOWN

PLASTIC DUAL−IN−LINE PACKAGE

DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
△C MS−001 VARIATION	AA	BB	AC	AD

A

16   9

0.260 (6,60)
0.240 (6,10)

1   8

0.070 (1,78)
0.045 (1,14) △D

0.045 (1,14)
0.030 (0,76) △D

0.020 (0,51) MIN

0.200 (5,08) MAX

Seating Plane

0.125 (3,18) MIN

0.100 (2,54)

0.021 (0,53)
0.015 (0,38)

⊕ 0.010 (0,25) Ⓜ

14/18 Pin Only
20 Pin vendor option △D

0.325 (8,26)
0.300 (7,62)

0.015 (0,38)

Gauge Plane

0.010 (0,25) NOM

0.430 (10,92) MAX

4040049/E 12/2002

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
         △C   Falls within JEDEC MS−001, except 18 and 20 pin minimum body length (Dim A).
         △D   The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R−PDSO−G14) PLASTIC SMALL−OUTLINE PACKAGE

0.344 (8,75)
0.337 (8,55)

14

8

0.244 (6,20)
0.228 (5,80)

0.157 (4,00)
0.150 (3,80)

1

7

Pin 1
Index Area

0.050 (1,27)

0.020 (0,51)
0.012 (0,31)

⊕ | 0.010 (0,25) Ⓜ

0.069 (1,75) Max

0.010 (0,25)
0.004 (0,10)

0.010 (0,25)
0.007 (0,17)

Gauge Plane

⌂ | 0.004 (0,10)

Seating Plane

0.010 (0,25)

0°−8°

0.050 (1,27)
0.016 (0,40)

4040047−3/F 07/2004

NOTES: A. All linear dimensions are in inches (millimeters).
        B. This drawing is subject to change without notice.
        C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
        D. Falls within JEDEC MS−012 variation AB.

NS (R-PDSO-G)**   PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN

PINS **DIM	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES: A.   All linear dimensions are in millimeters.
         B.   This drawing is subject to change without notice.
         C.   Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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